Product End-of-Life Disassembly Instructions

Product Category: POWER SUPPLY
Marketing Name / Model [List multiple models if applicable.]
MODEL: J9405B (HP ProCurve MSM31x and MSM32x PS)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
晶體	Epoxy+Alloy+Solder non-recyclable	
EMI shield	Aluminum	
Capacitors	Non-recyclable	14
Resistor		
Socket		
Wire		
Case		
Heat sink		
Tape		
Tube		
Screw		
Label	Paste on case	
Inductor		
Transformer		
PCB	Non recyclable	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
pliers.	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take out plastic mat and screw.
2. Take out plastic case.
3. Take out EMI Shielding case.
4. Take out mylar film.
6. Take out mix wire.
7. Take out heatsink.
8. Take out copper.
9. Take out socket.
10. Take out solder.
11. Take out inductors.
12. Take out transformer.
13. Take out big capacitor.
14. Left PCBA.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).